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ABSTRACT OF THE DISCLOSURE

A semiconductor chip mounting component includes a support structure adapted for engagement with a semiconductor chip having a top surface, a bottom surface and a gap extending through the support structure between the surfaces and defining first and second portions of the support structure on opposite sides of the gap. The semiconductor chip mounting component also includes at least one elongated bus disposed alongside the gap, on the second portion of the support structure, and a plurality of electrically conductive leads, each lead having a connection section extending across the gap, the connection section having a first end disposed on the first portion of the support structure and a second end secured to the bus, and a frangible section. The gap is open at the bottom surface of the support structure, and the leads are adapted to be bonded to contacts on a semiconductor chip disposed beneath the bottom surface by breaking the frangible sections of the leads so as to disconnect the second ends of the leads from the bus and engage the leads with the contacts of the chip.